

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L7	498685	polish\$6 or CMP or "chemical mechanical polishing" or grind\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
2	BRS	L8	5500	scribe adj line	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
3	BRS	L9	194674 3	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
4	BRS	L10	40287	bond\$6 adj pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
5	BRS	L11	118173 0	buffer\$6 or PR or photoresist or photo-resist or resist or photosensitivie	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L12	872497	periphery	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
7	BRS	L13	55	7 and 8 and 9 and 10 and 11 and 12	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:06
8	BRS	L14	176914 7	slurry or slurries or particles or impurit\$4 or contaminate\$4 or swarf	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:07
9	BRS	L15	21340	(backside or (back adj side)) near4 9	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09
10	BRS	L16	1469	7 near8 15	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L17	219	16 same 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
12	BRS	L18	25	17 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
13	BRS	L35	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
14	BRS	L36	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
15	BRS	L37	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
16	BRS	L38	4	6214441.URPN.	USPAT	2004/04/30 15:37
17	BRS	L41	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:38
18	BRS	L42	8	grinding and tape and (backside near4 wafer) and (scribe adj line) and interconnect	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:34
19	BRS	L43	26660	(polish\$6 or grind\$6 or dispers\$6 or abras\$6) near4 wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35

	Type	L #	Hits	Search Text	DBs	Time Stamp
20	BRS	L44	1459	43 and dicing	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35
21	BRS	L45	538	44 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35
22	BRS	L46	235	45 and 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:24
23	IS&R	L47	2502	(438/106).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:24
24	BRS	L48	70	47 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
25	BRS	L50	67	49 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:33
26	IS&R	L51	189	(438/115).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:47
27	BRS	L52	6	51 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:47
28	BRS	L53	7	("5155068" "5888883" "5977641" "5989982" "6107164" "6159837" "6287893").PN.	USPAT	2004/04/30 17:59
29	IS&R	L54	636	(438/459).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
30	BRS	L55	272	54 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:03
31	BRS	L56	59	55 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:03
32	IS&R	L57	1165	(438/118).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:37
33	BRS	L59	17	(buffer near2 coat\$6) near8 (polybenzoxazole or PBO)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 19:08

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L7	498685	polish\$6 or CMP or "chemical mechanical polishing" or grind\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
2	BRS	L8	5500	scribe adj line	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
3	BRS	L9	194674 3	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
4	BRS	L10	40287	bond\$6 adj pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
5	BRS	L11	118173 0	buffer\$6 or PR or photoresist or photo-resist or resist or photosensitivie	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L12	872497	periphery	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
7	BRS	L13	55	7 and 8 and 9 and 10 and 11 and 12	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:06
8	BRS	L14	176914 7	slurry or slurries or particles or impurit\$4 or contaminate\$4 or swarf	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:07
9	BRS	L15	21340	(backside or (back adj side)) near4 9	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09
10	BRS	L16	1469	7 near8 15	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L17	219	16 same 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
12	BRS	L18	25	17 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
13	BRS	L35	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
14	BRS	L36	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
15	BRS	L37	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
16	BRS	L38	4	6214441.URPN.	USPAT	2004/04/30 15:37
17	BRS	L41	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:38

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	5500	"scribe lines"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 10:57
2	BRS	L2	647324 7	surface	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 10:57
3	BRS	L3	236707	grinding	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 10:58
4	BRS	L4	557330	tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 10:58
5	BRS	L6	9193	(backside near2 (wafer or substrate))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 10:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L7	19	1 and 2 and 3 and 4 and 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:04
7	BRS	L8	255033	polish\$6 or CMP or "chemical mechanical polishing"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:05
8	BRS	L9	48511	bond\$6 near2 pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:06
9	BRS	L10	194674 3	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:06
10	BRS	L11	891815	adhesive	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:06

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L12	1570	8 and 9 and 10 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:07
12	BRS	L13	386	8 near4 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:07
13	BRS	L14	10	13 and 1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:09
14	BRS	L15	126	13 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:10
15	BRS	L16	25	15 and 9	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:13

	Type	L #	Hits	Search Text	DBs	Time Stamp
16	BRS	L17	7637	tape near8 adhesive near8 (wafer or substrate)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:14
17	BRS	L18	48141	8 near8 (wafer or substrate)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:15
18	BRS	L19	268	17 and 18	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 11:15

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L34	48511	bond\$6 near2 pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:03
2	BRS	L35	640147 5	aperture or via or opening or hole or gap or through-hole or (through adj hole)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:04
3	BRS	L36	118165 9	buffer\$4 or photoresist or PR or resist	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:05
4	BRS	L38	255033	polish\$6 or CMP or "chemical mechanical polishing"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:06
5	BRS	L39	194674 3	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:06

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L40	252320	slurry or slurries	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:06
7	BRS	L41	1876	34 same 35 same 36	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:07
8	BRS	L42	1005	41 same 39	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:07
9	BRS	L43	52	42 same 38	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:42
10	BRS	L44	226	42 and 38	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:42

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L45	174	44 not 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:50
12	IS&R	L46	2502	(438/106).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:51
13	IS&R	L48	1165	(438/118).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:51
14	IS&R	L49	636	(438/459).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:51
15	IS&R	L50	189	(438/115).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/29 20:56

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L7	498685	polish\$6 or CMP or "chemical mechanical polishing" or grind\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
2	BRS	L8	5500	scribe adj line	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:57
3	BRS	L9	194674 3	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
4	BRS	L10	40287	bond\$6 adj pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
5	BRS	L11	118173 0	buffer\$6 or PR or photoresist or photo-resist or resist or photosensitivie	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L12	872497	periphery	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 14:58
7	BRS	L13	55	7 and 8 and 9 and 10 and 11 and 12	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:06
8	BRS	L14	176914 7	slurry or slurries or particles or impurit\$4 or contaminate\$4 or swarf	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:07
9	BRS	L15	21340	(backside or (back adj side)) near4 9	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09
10	BRS	L16	1469	7 near8 15	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:09

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L17	219	16 same 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
12	BRS	L18	25	17 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 15:13
13	BRS	L35	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
14	BRS	L36	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
15	BRS	L37	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:37
16	BRS	L38	4	6214441.URPN.	USPAT	2004/04/30 15:37
17	BRS	L41	2	("3936301" "5509974").PN.	USPAT	2004/04/30 15:38
18	BRS	L42	8	grinding and tape and (backside near4 wafer) and (scribe adj line) and interconnect	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:34
19	BRS	L43	26660	(polish\$6 or grind\$6 or dispers\$6 or abras\$6) near4 wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35

	Type	L #	Hits	Search Text	DBs	Time Stamp
20	BRS	L44	1459	43 and dicing	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35
21	BRS	L45	538	44 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 16:35
22	BRS	L46	235	45 and 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:24
23	IS&R	L47	2502	(438/106).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:24
24	BRS	L48	70	47 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
25	BRS	L50	67	49 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:33
26	BRS	L52	6	51 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 17:47
27	BRS	L53	7	("5155068" "5888883" "5977641" "5989982" "6107164" "6159837" "6287893") .PN.	USPAT	2004/04/30 17:59
28	BRS	L55	272	54 and 43	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:03
29	BRS	L56	59	55 and tape	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:03

	Type	L #	Hits	Search Text	DBs	Time Stamp
30	IS&R	L57	1165	(438/118).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 18:37
31	BRS	L59	17	(buffer near2 coat\$6) near8 (polybenzoxazole or PBO)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 19:08
32	IS&R	L60	189	(438/115).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 19:56
33	IS&R	L61	636	(438/459).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/30 20:50